JPCA 2027 Show
56th International Electronic Circuits Exhibition

JIEP 2027 Microelectronics Show
41st ADVANCED ELECTRONICS PACKAGING EXHIBITION

JISSO PROTEC 2027
28th Jisso Process Technology Exhibition

CORE TECHNOLOGIES Expo
AI / Photonic-Electronic Integration

Connecting Machine to Machine
WIRE Japan Show
Electrical /Optical Transmission Technology

Electronics Component & Unit Show
Japan Federation of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association

E-Textile/Wearable

OSAT SOLUTION SHOW



The Exhibition Guide

2027.6.2 Wed. → 4 Fri.

Tokyo Big Sight, East Exhibition Halls

The Total Solution Exhibition for Electronic Equipment 2027

Exhibitor Applications Open at 10:00 am (JST), on Monday, November 2, 2026

Official Website

Organizers: Japan Electronics Packaging and Circuits Association, Japan Institute of Electronics Packaging, Japan Robot Association

Co-organizers: Electronic Device Industry News (Sangyo Times, Inc.)
Electric Wire & Cable News(Densen Shimbunsha CO,.Ltd.)
Japan Federation Of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association
Japan OSAT Federation

Sponsor (tentative): Ministry of Economy, Trade and Industry

Overseas Cooperation:
World Electronic Circuits Council (WECC) Member Associations:
China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC),
Electronic Industries Association of India (ELCINA),Hong Kong Printed Circuit Association (HKPCA),
Global Electronics Association (GEA), Indian Printed Circuit Association (IPCA),
Korea Semiconductor Packaging and Circuits Association (KPCA), Thailand Printed Circuit Association (THPCA),
Taiwan Printed Circuit Association (TPCA)

Korea Packaging Integration Association-JKC (KPIA)

As of Oct.29, 2026

" What Is the Future Made Of ?

– From Semiconductors, PCBs, and Packaging Technologies to Electronics for the AI Era –"

At Total Solution Exhibition for Electronic Equipment 2027, a wide range of technologies and products shaping the future of electronics will come together under one roof, spanning semiconductors, packaging, printed circuit boards (PCBs), electronics assembly, materials and equipment, electronic components, and finished electronic products.

Introducing the new "CORE TECHNOLOGIES Expo 2027 – AI / Photonic-Electronic Integration"!
Key technologies supporting AI and photonic-electronic integration come together in one place!

Exhibition Outline

Exhibition Period Wednesday, June 2 to Friday, June 4, 2027, 10:00 a.m. - 5:00 p.m. JST

Venue Tokyo Big Sight East Exhibition Halls

Admission JPY 1,000 (including tax)
* Free Admission for those who have pre-registered online.

Managed by Japan Electronics Packaging and Circuits Association (JPCA)

Secretariat Office Power Project Co., Ltd.

Exhibitors

Electronic circuits technology

JPCA 2027 Show
56th International Electronic Circuits Exhibition

Organizer:
Japan Electronics Packaging and Circuits Association

- **PWB Tech**
  Products and Technologies related to electronic circuit boards (Design & Simulation, Reliability& Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment,Related Systems), etc.
- **Module JAPAN**
  Module board / Module Board mounting / Embedded Component Board, General technology for built-in parts (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems) ,etc.
- **Flexible Printed Circuits Products Area**
  General technology for Flexible Printed Circuits (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems)
- **EMS Japan**
  Services and technologies related to EMS, ODM and contract manufacturing of semiconductors (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems)

High-density packaging technologies

JIEP 2027 Microelectronics Show
41st ADVANCED ELECTRONICS PACKAGING EXHIBITION

Organizer:
Japan Institute of Electronics Packaging

General technology for implementation and electric technology
(Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)

Electronic Component Packaging Technologies

JISSO PROTEC 2027
28th Jisso Process Technology Exhibition

Organizer: Japan Robot Association

- Electronic Component Placement Machines and related Equipment and Systems: electronic component placement machines (Mounter), electronic component insertion machines (Inserter), screen printers, soldering equipment (reflow oven), and dispensers
- Packaging related Equipment and Systems: transfer systems, AGV, automatic warehouse, taping machines and materials, bulk feeders and other feeders, and automatic assembly machines, laser marking machine, cleaning equipment · cleaner
- Semiconductor Packaging Machines and Systems: bonding equipment, flip chip packaging systems,COB systems
- Industrial Robotics: handling robots, assembly robots, transport robots
- Inspection/Test Equipment: automated optical inspection equipment, inspection/measuring equipment associated with semiconductor manufacturing
- Packaging Design Systems: design tools, production optimizing software, and packaging programming equipment
- Packaging Device Packaging Materials
- Packaging Joining Systems · Solder/joining materials
- High Frequency Compatible Devices, Components, and Materials
- Environment related Devices and Materials

AI & Photonic-Electronic Integration Technologies

NEW CORE TECHNOLOGIES Expo
AI / Photonic-Electronic Integration

Co-organizers:
Japan Electronics Packaging and Circuits Association,
Electronic Device Industry News (Sangyo Times Inc.)

The exhibition covers key technologies that enable high-speed, high-capacity, and energy-efficient performance for AI data centers, AI servers, and next-generation computing.

- **Photonic-Electronic Integration & Photonics**
  Silicon photonics / Optical I/O / CPO & LPO / Optical transceivers / Optical switches / Lasers & photonic devices / Optical waveguides / Photonic-electronic integration & optical packaging technologies
- **AI Computing & High-Speed Data Transmission**
  AI semiconductors / GPUs & AI accelerators / High-speed interfaces / SerDes / High-speed transmission components / EMI solutions
- **Advanced Packaging & Electronics Assembly**
  2.5D & 3D packaging / Chiplets / Interposers / Glass substrates & glass-core substrates / High-density packaging & bonding technologies
- **High-Speed & High-Frequency PCBs and Materials**
  High-speed, high-frequency & low-loss PCBs / Photonic-electronic integrated PCBs / Low-dielectric, high-heat-resistance & thermal-management materials / Next-generation PCB materials
- **Power, Cooling & Thermal Management**
  Power modules / Power semiconductors / DC-DC converters / Busbars / Liquid & air cooling / Heat dissipation & thermal management technologies
- **Manufacturing, Design, Inspection & Evaluation**
  Manufacturing & assembly equipment / Design & EDA / Simulation / Inspection & measurement / High-speed signal & optical communications testing / Reliability testing, etc.

Electrical/optical transmission technology

Connecting Machine to Machine
WIRE Japan Show
Electrical /Optical Transmission Technology

Co-organizers:
Japan Electronics Packaging and Circuits Association,
Electric Wire & Cable News(Densen Shimbunsha CO,.Ltd.)

General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)

Semiconductors and Electronic parts

Electronics Component & Unit Show
Japan Federation of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association

Co-organizers:
Japan Electronics Packaging and Circuits Association,
Japan Federation Of Electronic Parts Distributors And Dealers,
Tokyo Electronics Appliances Wholesalers Association

General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)

Highly functional textile

E-Textile/Wearable

Organizer:
Japan Electronics Packaging and Circuits Association

A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)

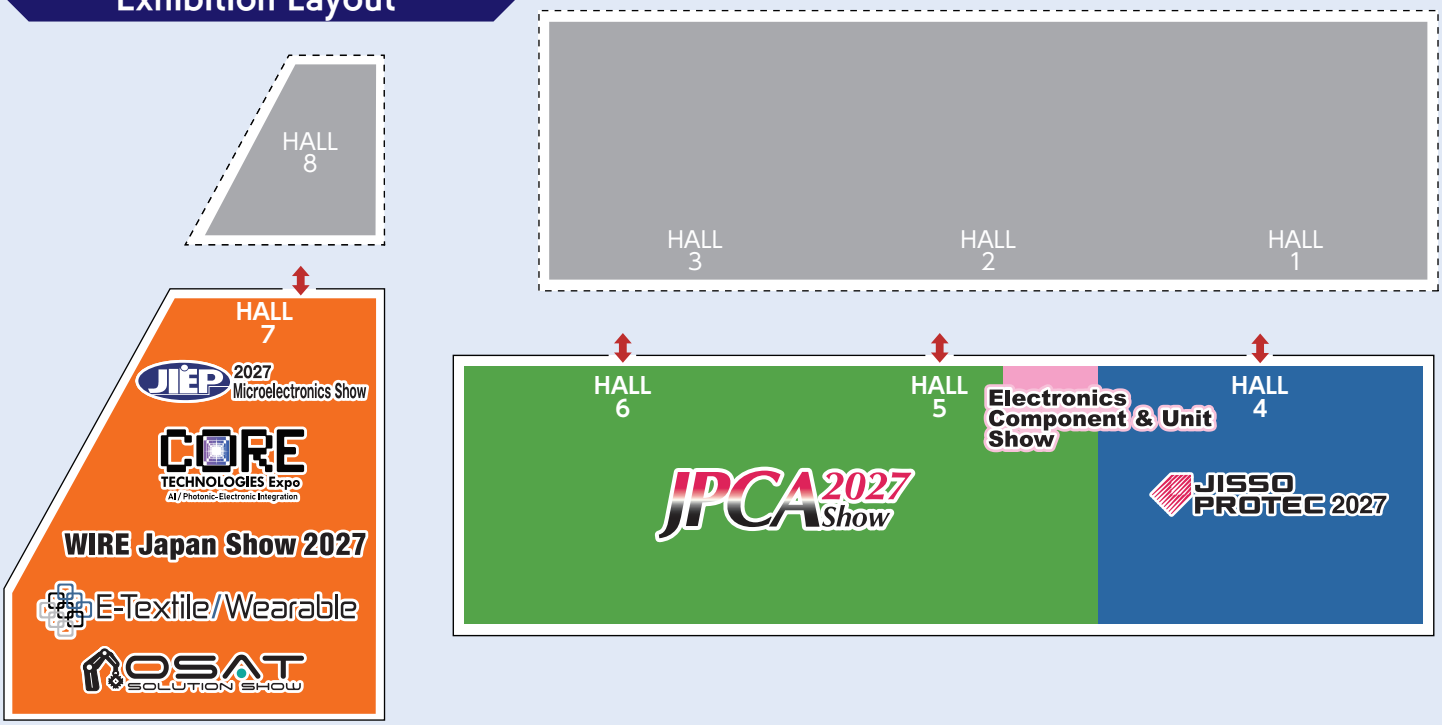
Semiconductor OSAT

OSAT SOLUTION SHOW

Co-organizers:
Japan Electronics Packaging and Circuits Association, Japan OSAT Federation

Comprehensive technologies / materials / equipment related to semiconductor back-end processes (package materials, assembly equipment, wafer-level packages, fan-out packages (FO-WLP / FO-PLP), 3D / 2.5D assembly, chiplets, PLP, test systems, handling equipment, package design tools, simulators, etc.)
Trading companies / organizations / others related to semiconductor back-end processes

Exhibition Layout



2026 Exhibition Results

Venue Tokyo Big Sight East Exhibition Halls

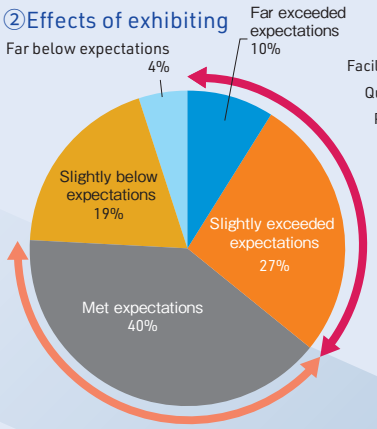
Exhibition 534 companies / 1,373 booths **Number of visitors** 49,206 people

Exhibitors Questionnaire

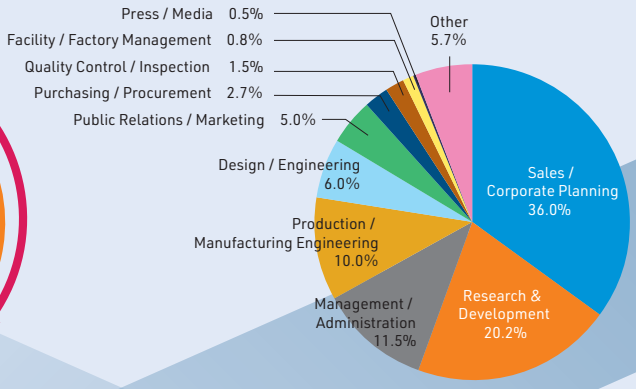
①Reasons for exhibiting (Multiple responses)



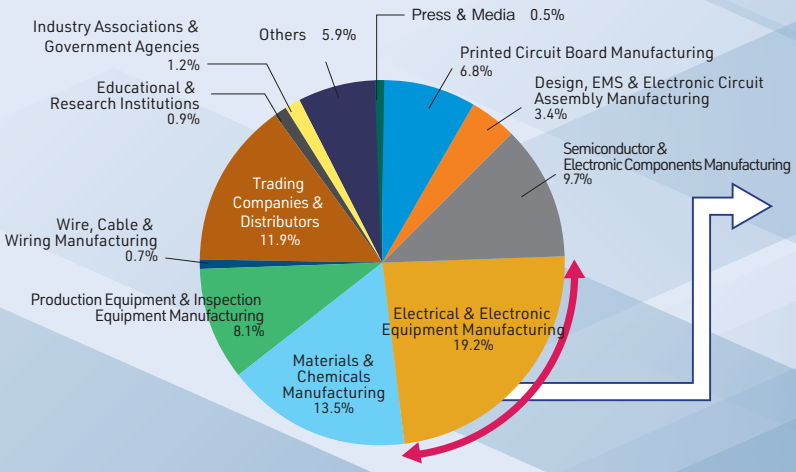
②Effects of exhibiting



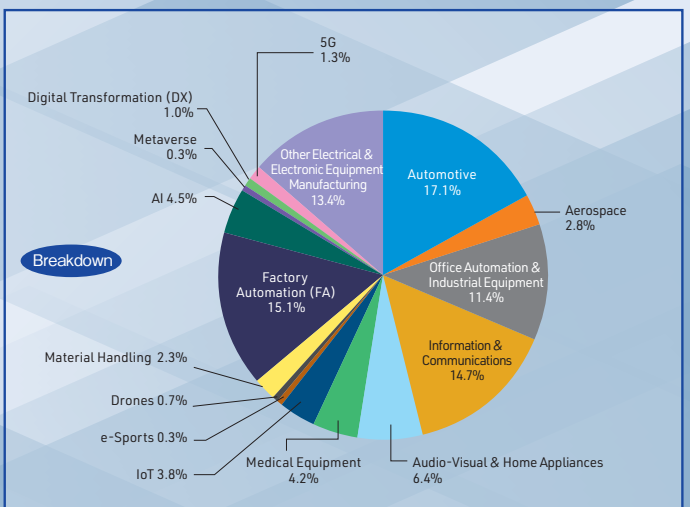
Job classification of Visitors



Industry Classification of Visitors



Breakdown



As a comprehensive exhibition, the event brings together professionals from a broad range of electronics-related industries, particularly those involved in electrical and electronic equipment manufacturing. The information and communications and factory automation sectors have seen especially strong growth in attendance. Visitors have also shown strong interest in printed circuit boards, electronic circuit assembly, and semiconductor packaging products.

Exhibition Fee

Category		1 booth/9m² *Tax included
Non-Members		JPY 498,300
JPCA Members,Overseas Members*1	Regular	JPY 424,600
JPCA Members	Early	JPY 398,200

*1 Members of the following associations
WECC Member Associations (CPCA, EIPC, ELCINA, HKPCA, GEA, IPCA, KPCA, THPCA, TPCA), KPIA

※ Size of a booth is 9m² (3m × 3m).

※ Fee is for raw space only, Booth construction, cleaning, electricity, water supply, etc. are not included in the exhibition fee.

How to apply (From Monday,November 2,2026, 10:00 a.m. JST)

Please apply online via the exhibition website (www.jpcashow.com).
Select the exhibition section that best matches your company's products, technologies, and services, and be sure to review the Exhibition Regulations.
For exhibitions with a dedicated application form, the corresponding regulations will apply.
After receiving your application form, an invoice will be issued. Please make payment by the specified deadline (in principle, payment is required before the exhibition).

Application Deadline

Early Application Deadline (Member Companies Only)	**Friday, January 29,2027**
Final application deadline	**Friday, February 26, 2027**

※Please see the Exhibitor Fee section for early-bird rates and eligibility requirements.
※If all spaces are reserved before the deadline, the application will no longer be accepted.

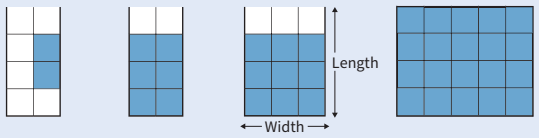
Cancellation Fees

If an exhibitor cancels its participation for any reason, cancellation fees will apply as follows.

Date of receipt of written notice of cancellation	Cancellation charges
Until Friday,February 26,2027	30% of booth fees
Saturday,February 27 –Wednesday,March 31,2027	50% of booth fees
Thursday,April 1 – Friday,April 30	70% of booth fees
From Saturday,May 1	100% of booth fees

Booth type

(A) In-line　(B) Block (four or more units)　(C) Island (20 or more units)



※ In some cases, it may not be possible to prepare the requested booth type.

Assignment of Booth Locations

Booths will be assigned at the Booth Location Selection Meeting (Scheduled to be held in late March 2027).
As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis.
※For details, please refer to the Exhibitor Rules and Regulations.

Exhibitor Support Program　Option

Promotion services will provide an opportunity to increase your presence at the exhibition.
※For details, please refer to the On-Demand Exhibitor Briefing (around mid-March 2027).

Package booth　Option

●1 booth / basic plan(Tentative)
Price: JPY 121,000 (Tax included)
This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.
For more details, please refer to the document to be distributed around mid-March 2027.



Schedule

2026 Nov.	2027 Jan.	Feb.	Mar.	Apr.	Jun.
▲ November2,(Mon.) 10:00 – JST Start of Exhibition Application	▲ January 29(Fri.) Early Application Deadline (Member Companies Only)	▲ February 26(Fri.) Exhibitor application deadline	▲ Mid-March On-Demand Exhibitor Briefing Exhibitor Manual available ▲ Late March Booth Location Selection Meeting	▲ Mid-April Sending Invitations Visitor Registration begins	▲ May 31,(Mon.)-June 1(Tue.) Installation period June2,(Wed.)-June4(Fri.) Exhibition open ※Immediate removal on the last day

Submission of necessary forms

Managed by
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TEL:+81-3-5310-2020　E-mail: show@jpca.org

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TEL:+81-03-6823-1414　E-mail:jpca@powerproject.co.jp

Official Website